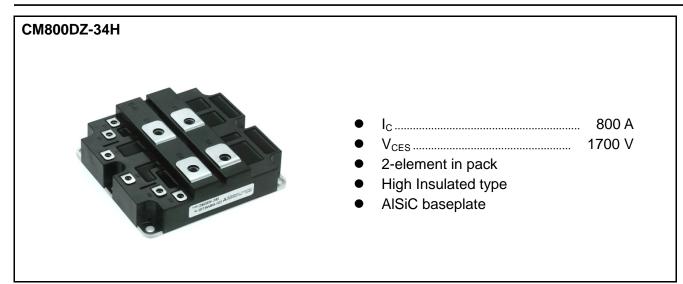


# <High Voltage Insulated Gate Bipolar Transistor: HVIGBT >

# CM800DZ-34H

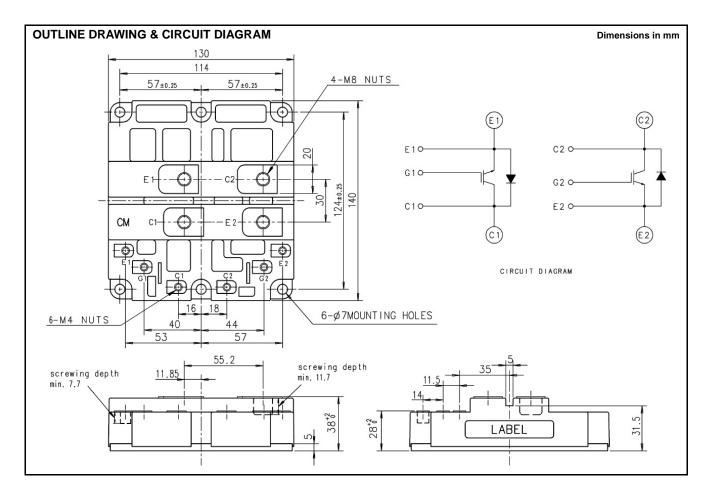
HIGH POWER SWITHCHING USE INSULATED TYPE

3rd-Version HVIGBT (High Voltage Insulated Gate Bipolar Transistor) Modules



# APPLICATION

Traction drives, High Reliability Converters / Inverters, DC choppers



### MAXIMUM RATINGS

Symbol	Item	Conditions	Ratings	Unit
V <sub>CES</sub>	Collector-emitter voltage	$V_{GE} = 0V, T_j = 25^{\circ}C$	1700	V
$V_{\text{GES}}$	Gate-emitter voltage	$V_{CE} = 0V, T_j = 25^{\circ}C$	± 20	V
lc	Callester surrent	DC, $T_c = 80^{\circ}C$	800	А
I <sub>CRM</sub>	Collector current	Pulse (Note 1)	1600	А
l <sub>E</sub>	Emitter current (Note 2)	DC	800	А
I <sub>ERM</sub>	Emitter current (Note 2)	Pulse (Note 1)	1600	А
P <sub>tot</sub>	Maximum power dissipation (Note 3)	$T_c = 25^{\circ}C$ , IGBT part	6200	W
V <sub>iso</sub>	Isolation voltage	RMS, sinusoidal, f = 60Hz, t = 1 min.	4000	V
Tj	Junction temperature		-40 ~ +150	°C
T <sub>jop</sub>	Operating junction temperature		-40 ~ +125	°C
T <sub>stg</sub>	Storage temperature		-40 ~ +125	°C
t <sub>psc</sub>	Short circuit pulse width	$V_{CC} = 1150V, V_{CE} \leq V_{CES}, V_{GE} = 15V, T_j = 125^{\circ}C$	10	μs

# ELECTRICAL CHARACTERISTICS

Symbol	Item	Conditions		Limits			Unit
Symbol	Item			Min	Тур	Max	Unit
I <sub>CES</sub>	Collector cutoff current	$V_{CE} = V_{CES}$ , $V_{GE} = 0V$ , $T_i = 25^{\circ}C$		_	—	12.0	mA
V <sub>GE(th)</sub>	Gate-emitter threshold voltage	V <sub>CE</sub> = 10 V, I <sub>C</sub> = 80 mA, T <sub>j</sub> = 25°C		4.5	5.5	6.5	V
I <sub>GES</sub>	Gate leakage current	$V_{GE} = V_{GES}$ , $V_{CE} = 0V$ , $T_j = 25^{\circ}C$			—	0.5	μA
Cies	Input capacitance	$V_{CE} = 10 \text{ V}, \text{ V}_{GE} = 0 \text{ V}, \text{ f} = 100 \text{ kHz}$ $T_j = 25^{\circ}\text{C}$		_	72.0		nF
C <sub>oes</sub>	Output capacitance				9.0	_	nF
Cres	Reverse transfer capacitance				3.6	_	nF
$Q_{G}$	Total gate charge	V <sub>CC</sub> = 850V, I <sub>C</sub> = 800A, V <sub>GE</sub> = 15V, T <sub>j</sub> = 25°C		—	6.6	_	μC
	Collector-emitter saturation voltage	$I_{C} = 800 \text{ A}^{(Note 4)}$	T <sub>j</sub> = 25°C	_	2.60	3.30	
V <sub>CEsat</sub>		V <sub>GE</sub> = 15 V	T <sub>j</sub> = 125°C	_	3.10	_	V
t <sub>d(on)</sub>	Turn-on delay time	$V_{CC} = 850 \text{ V}, I_{C} = 800 \text{ A}, V_{GE} = \pm 15 \text{ V}$		_	—	1.60	μs
t <sub>r</sub>	Turn-on rise time	$R_{G(on)} = 3.3 \ \Omega, T_j = 125^{\circ}C, L_s = 150 \text{ nH}$ Inductive load		_	_	1.30	μs
E <sub>on(10%)</sub>	Turn-on switching energy (Note 5)			_	350	_	mJ
t <sub>d(off)</sub>	Turn-off delay time	$V_{CC} = 850 \text{ V}, I_{C} = 800 \text{ A}, V_{GE} = \pm 15 \text{ V}$	$V_{GC} = 850 \text{ V}$ , $I_C = 800 \text{ A}$ , $V_{GE} = \pm 15 \text{ V}$			2.70	μs
t <sub>f</sub>	Turn-off fall time	$R_{G(off)} = 3.3 \ \Omega, T_j = 125^{\circ}C, L_s = 150 \ nH$ Inductive load		_	_	0.50	μs
E <sub>off(10%)</sub>	Turn-off switching energy (Note 5)			_	260	_	mJ
N/	Emitter-collector voltage (Note 2)	I <sub>E</sub> = 800 A <sup>(Note 4)</sup>	T <sub>j</sub> = 25°C	_	2.30	_	N/
$V_{EC}$		$V_{GE} = 0 V$	T <sub>j</sub> = 125°C	_	2.00		V
t <sub>rr</sub>	Reverse recovery time (Note 2)	$V_{CC} = 850 \text{ V}, I_{C} = 800 \text{ A}, V_{GE} = \pm 15 \text{ V}$			—	2.70	μs
Q <sub>rr</sub>	Reverse recovery charge (Note 2)	$R_{G(on)} = 3.3 \Omega$ , $T_j = 125^{\circ}C$ , $L_s = 150 \text{ nH}$			300		μC
Erec(10%)	Reverse recovery energy <sup>(Note 2), (Note 5)</sup>	Inductive load		_	120	_	mJ

## THERMAL CHARACTERISTICS

Symbol	Item	Conditions	Limits			Unit
		Conditions		Тур	Max	Unit
R <sub>th(j-c)Q</sub>	Thermal resistance	Junction to Case, IGBT part, 1/2 module	l		20.0	K/kW
R <sub>th(j-c)D</sub>		Junction to Case, FWDi part, 1/2 module	l		34.0	K/kW
R <sub>th(c-s)</sub>	Contact thermal resistance	Case to heat sink, $\lambda_{grease} = 1W/m \cdot k$ , $D_{(c-s)} = 100 \mu m$ 1/2 module		16.0	_	K/kW

#### **MECHANICAL CHARACTERISTICS**

Symbol	ltem	Conditions		1.1		
			Min	Тур	Max	Unit
Mt		M8 : Main terminals screw	7.0	-	13.0	N∙m
Ms	Mounting torque	M6 : Mounting screw	3.0		6.0	N∙m
Mt		M4 : Auxiliary terminals screw	1.0		2.0	N∙m
m	Mass		-	1.0	_	kg
CTI	Comparative tracking index		250			_
da	Clearance		10.0	I		mm
ds	Creepage distance		15.0	-	_	mm
L <sub>P CE</sub>	Parasitic stray inductance	IGBT part, 1/2 module	_	18	_	nH
R <sub>CC'+EE'</sub>	Internal lead resistance	IGBT part, 1/2 module, T <sub>c</sub> = 25°C	_	0.16	_	mΩ

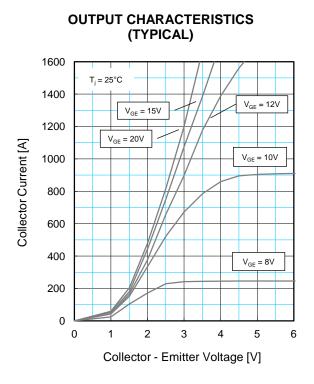
Note 1. Pulse width and repetition rate should be such that junction temperature  $(T_j)$  does not exceed  $T_{jopmax}$  rating.

Note 2. The symbols represent characteristics of the anti-parallel, emitter to collector free-wheel diode (FWD<sub>i</sub>).

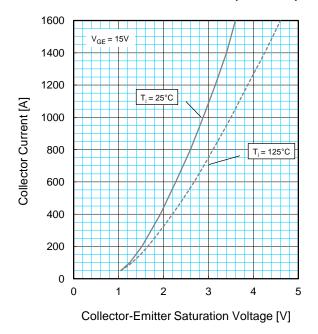
Note 3. Junction temperature  $(T_j)$  should not exceed  $T_{jmax}$  rating (150°C).

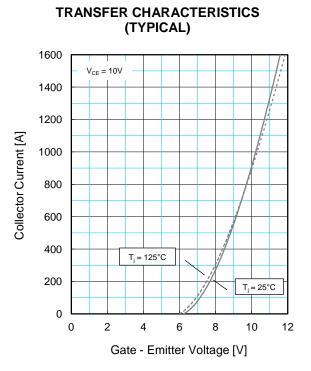
Note 4. Pulse width and repetition rate should be such as to cause negligible temperature rise.

Note 5.  $E_{on(10\%)}$  /  $E_{off(10\%)}$  /  $E_{rec(10\%)}$  are the integral of 0.1V<sub>CE</sub> x 0.1I<sub>C</sub> x dt.

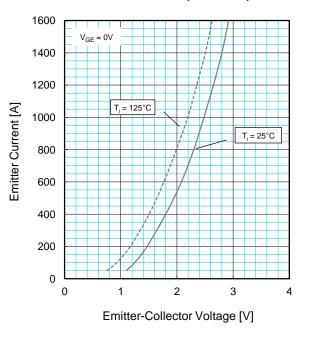


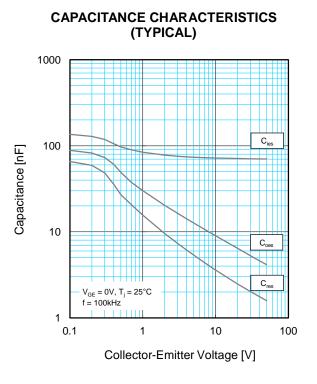
#### COLLECTOR-EMITTER SATURATION VOLTAGE CHARACTERISTICS (TYPICAL)



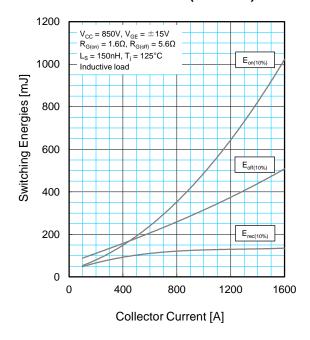


#### FREE-WHEEL DIODE FORWARD CHARACTERISTICS (TYPICAL)

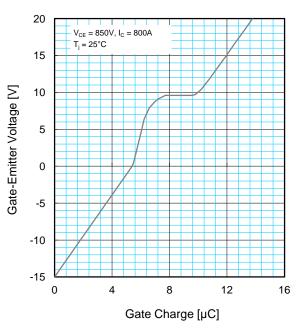




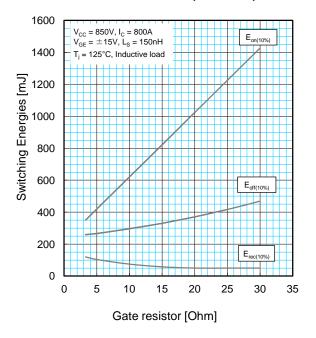
## HALF-BRIDGE SWITCHING ENERGY CHARACTERISTICS (TYPICAL)

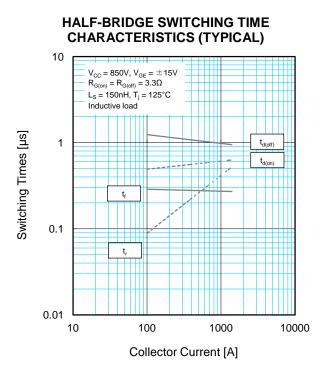


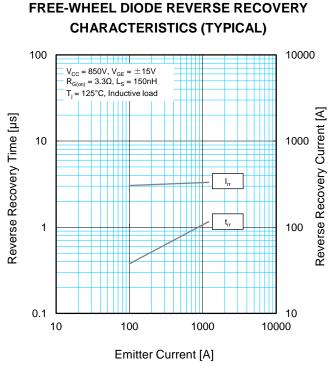
GATE CHARGE CHARACTERISTICS (TYPICAL)



HALF-BRIDGE SWITCHING ENERGY CHARACTERISTICS (TYPICAL)

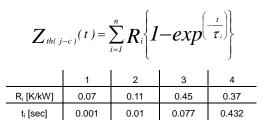


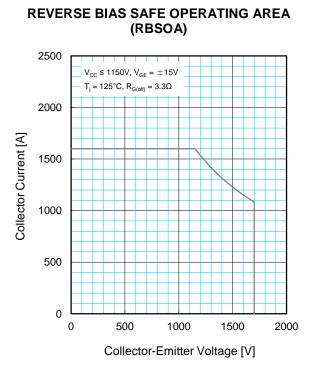




# 1.2 $R_{th(j-c)Q} = 20.0K/kW$ $R_{th(j-c)D} = 34.0K/kW$ Normalized Transient Thermal impedance 1 0.8 0.6 0.4 0.2 0 0.001 0.01 0.1 1 10 Time [s]

TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS





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